Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	(("6281111") or ("6097091")).PN.	USPAT; USOCR	OR	OFF	2003/10/26 11:35
S2	8	(("6136624") or ("5382544") or ("4654113") or ("6051489") or ("5859472") or ("5659203") or ("5790377") or ("5828128")).PN.	USPAT; USOCR	OR	OFF	2002/11/01 09:44
S3	17	semiconductor and (package or packaging) and ((face near down) near technique)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/11/01 09:49
S4	17	semiconductor and ((face near down) near technique) and electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/11/01 09:55
S5	44	toledo.xa.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/04/08 11:29
S6	0	((438/127).CCLS.) and (faced near down) same technique	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/11/01 09:55
S7	0	((438/127).CCLS.) and ((faced near down) same technique)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/11/01 09:56
S8	14	((438/127).CCLS.) and ((face near down) same technique)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/11/01 09:56
S9	666	(438/127).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/04/08 13:46
S10	0	((438/127).CCLS.) not(@ad>"19970519" or rlad>"19970519")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/11/01 10:01

S11	210	((438/127).CCLS.) not (@ad>"19970519" or @rlad>"19970519")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/04/08 14:33
S12	11	(("4597177") or ("5207887") or ("5346857") or ("5431328") or ("5477087") or ("5642261") or ("3795037") or ("4893172") or ("5518964") or ("5682061") or ("5763941")).PN.	USPAT; USOCR	OR	OFF	2002/11/01 10:21
S13	442	(438/108).CCLS.	USPAT; USOCR	OR	OFF	2002/11/01 10:21
S14	577	(438/108).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/11/01 10:21
S15	95	((438/108).CCLS.) not (@ad>"19970519" or @rlad>"19970519")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/04/08 11:30
S16	15	semiconductor and ((dielectric or insulating or encapsulant) same (polyimide near resin)) and ((flip near chip) same (polyimide near resin))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/11/01 10:59
S17	306	semiconductor and (polyimide near resin) and (flip near chip) and (package or packaging or packaged)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/04/08 13:40
S18	93	(semiconductor and (polyimide near resin) and (flip near chip) and (package or packaging or packaged)) not (@ad>"19970519" or @rlad>"19970519")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2002/11/01 11:01
S19	68	toledo.xa.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2003/04/08 11:29
S20	95	((438/108).CCLS.) not (@ad>"19970519" or @rlad>"19970519")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2003/04/08 11:30
S21	93	semiconductor and (polyimide near resin) and (flip near chip) and (package or packaging or packaged) not (@ad>"19970519" or @rlad>"19970519")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/04/08 13:45

S22	244	438/127 not (@ad>"19970519" or @rlad>"19970519")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/04/08 14:06
S23	1	"09/793,493"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/04/08 14:06
S24	210	((438/127).CCLS.) not (@ad>"19970519" or @rlad>"19970519")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2003/04/08 14:34
S25	40	electrode with (bond near pad) same resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/04/08 14:39
S26	22	(electrode with (bond near pad) same resin) not (@ad>"19970519" or @rlad>"19970519")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/04/08 14:40
S27	76731	Oki.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/26 11:36
S28	9	Oki.as. and (Ohsumi.in.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/10/26 11:36
S29	0	(flip near chip) and (seal$3 near (film or laminate or member or layer or resin)) not (@ad>"19970519" or rlad>"19970519")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/15 16:48
S30	0	(semiconductor) and (seal$3 near (film or laminate or member or layer or resin)) not (@ad>"19970519" or rlad>"19970519")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/15 16:48
S31	0	(flip near chip) and (seal$3 near (film or laminate or member or layer or resin)) not (@ad>"19970519" or rlad>"19970519")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/15 16:51

S32	0	(semiconductor) and (seal$3 near (film or laminate or member or layer or resin)) not (@ad>"19970519" or rlad>"19970519")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/15 16:56
S33	0	(semiconductor) and (encapsulating near (film or laminate or member or layer or resin)) not (@ad>"19970519" or rlad>"19970519")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/15 16:56
S34	2	"6713319"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/16 15:40
S35	13	(("6136624") or ("5382544") or ("4654113") or ("6051489") or ("5859472") or ("5659203") or ("5790377") or ("5828128") or ("5478778") or ("5959940") or ("6281111") or ("5864178") or ("5534465")).PN.	USPAT	OR	OFF	2004/12/16 15:48
S36	1	("5989940").PN.	USPAT	OR	OFF	2004/12/16 15:42
S37	6	(("5291066") or ("6255737") or ("5534731") or ("5909056") or ("5731630") or ("5834338")).PN.	USPAT	OR	OFF	2004/12/16 15:49